



Material Composition Declaration

EPC2361

Company Name	Efficient Power Conversion (EPC)	Issue Date:	6/30/2025
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	35.8 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	9.5443	26.6531	27.8115	266531
	Silicon oxide	7631-86-9	0.0724	0.2021		2021
	Silicon nitride	12033-89-5	0.0520	0.1451		1451
	Gallium nitride	25617-97-4	0.0531	0.1483		1483
	Aluminum	7429-90-5	0.0004	0.0011		11
	Aluminum nitride	24304-00-5	0.0097	0.0272		272
	Titanium	7440-32-6	0.0036	0.0101		101
	Titanium nitride	25583-20-4	0.0642	0.1792		1792
	Copper	7440-50-8	0.0000	0.0000		0
	Tungsten	7440-33-7	0.0204	0.0569		569
	Polyimide		0.1391	0.3883		3883
Under Bump Metal	Titanium	7440-32-6	0.0010	0.0027	0.0292	27
	Copper	7440-50-8	0.0095	0.0265		265
Solder Bump	Copper	7440-50-8	1.0251	2.8625	3.6782	28625
	Nickel	7440-02-0	0.0566	0.1581		1581
	Tin	7440-31-5	0.2312	0.6458		6458
	Silver	7440-22-4	0.0042	0.0118		118
Package	Copper	7440-50-8	11.7262	32.7462	68.4811	327462
	Iron	7439-89-6	0.3007	0.8396		8396
	Mold Compound		11.8099	32.9798		329798
	Tin	7440-31-5	0.6859	1.9155		19155
Sum in total:			35.8094	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.